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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	33MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	66
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	678 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	84-LCC (J-Lead)
Supplier Device Package	84-PLCC (29.31x29.31)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c762-33e-l

5.0 RESET

The PIC17CXXX differentiates between various kinds of RESET:

- Power-on Reset (POR)
- Brown-out Reset
- MCLR Reset
- WDT Reset

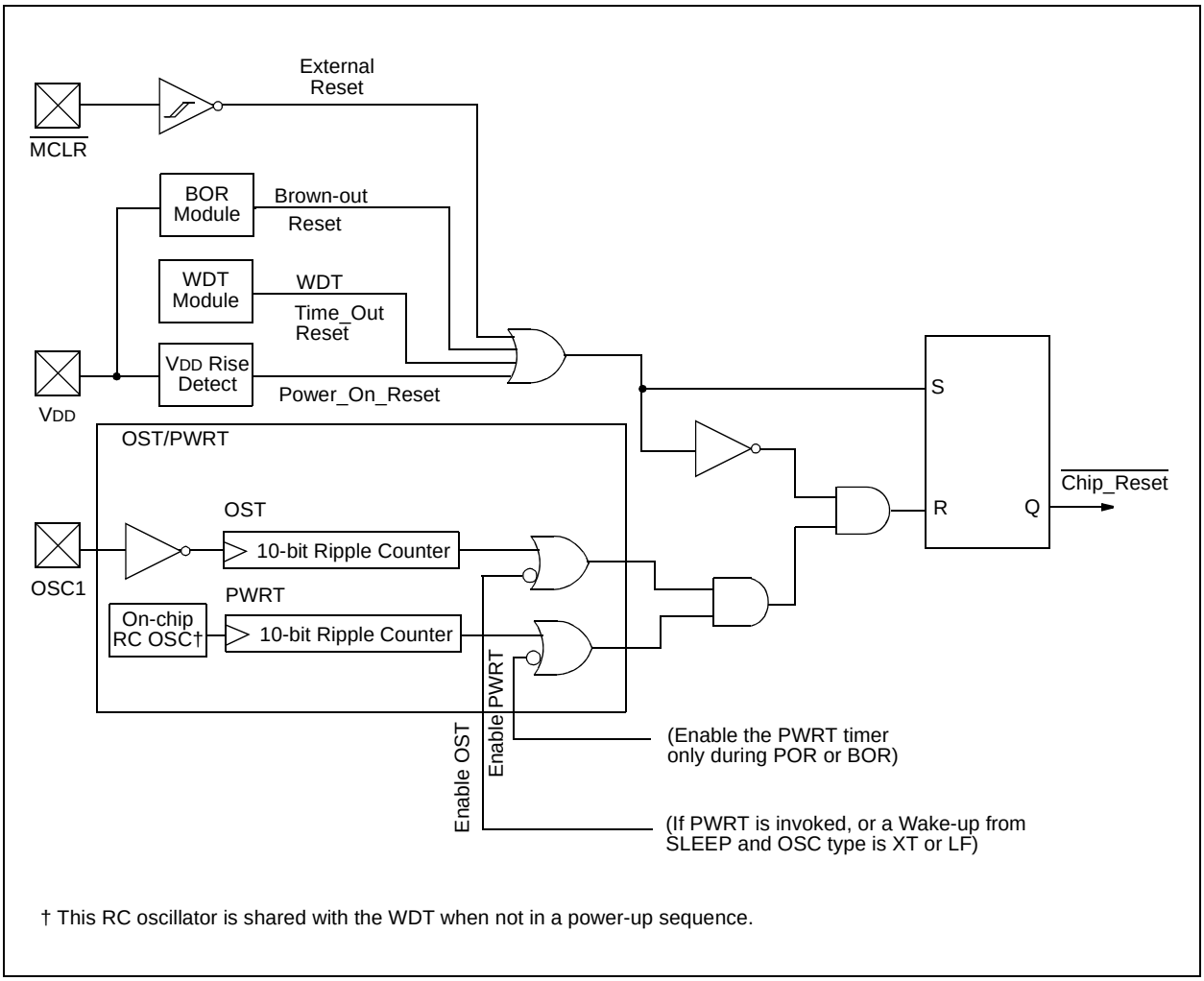
Some registers are not affected in any RESET condition, their status is unknown on POR and unchanged in any other RESET. Most other registers are forced to a "RESET state". The TO and PD bits are set or cleared differently in different RESET situations, as indicated in Table 5-3. These bits, in conjunction with the POR and BOR bits, are used in software to determine the nature of the RESET. See Table 5-4 for a full description of the RESET states of all registers.

When the device enters the "RESET state", the Data Direction registers (DDR) are forced set, which will make the I/O hi-impedance inputs. The RESET state of some peripheral modules may force the I/O to other operations, such as analog inputs or the system bus.

Note:	While the device is in a RESET state, the internal phase clock is held in the Q1 state. Any processor mode that allows external execution will force the RE0/ALE pin as a low output and the RE1/OE and RE2/WR pins as high outputs.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 5-1.

FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



† This RC oscillator is shared with the WDT when not in a power-up sequence.

FIGURE 7-5: PIC17C7XX REGISTER FILE MAP

Addr	Unbanked
00h	INDF0
01h	FSR0
02h	PCL
03h	PCLATH
04h	ALUSTA
05h	T0STA
06h	CPUSTA
07h	INTSTA
08h	INDF1
09h	FSR1
0Ah	WREG
0Bh	TMR0L
0Ch	TMR0H
0Dh	TBLPTRL
0Eh	TBLPTRH
0Fh	BSR

	Bank 0	Bank 1(1)	Bank 2(1)	Bank 3(1)	Bank 4(1)	Bank 5(1)	Bank 6(1)	Bank 7(1)	Bank 8(1,4)
10h	PORTA	DDRC	TMR1	PW1DCL	PIR2	DDRF	SSPADD	PW3DCL	DDRH
11h	DDRB	PORTC	TMR2	PW2DCL	PIE2	PORTF	SSPCON1	PW3DCH	PORTH
12h	PORTB	DDRD	TMR3L	PW1DCH	—	DDRG	SSPCON2	CA3L	DDRJ
13h	RCSTA1	PORTD	TMR3H	PW2DCH	RCSTA2	PORTG	SSPSTAT	CA3H	PORTJ
14h	RCREG1	DDRE	PR1	CA2L	RCREG2	ADCON0	SSPBUF	CA4L	—
15h	TXSTA1	PORTE	PR2	CA2H	TXSTA2	ADCON1	—	CA4H	—
16h	TXREG1	PIR1	PR3L/CA1L	TCON1	TXREG2	ADRESL	—	TCON3	—
17h	SPBRG1	PIE1	PR3H/CA1H	TCON2	SPBRG2	ADRESH	—	—	—

	Unbanked
18h	PRODL
19h	PRODH
1Ah 1Fh	General Purpose RAM

	Bank 0(2)	Bank 1(2)	Bank 2(2)	Bank 3(2,3)
20h FFh	General Purpose RAM	General Purpose RAM	General Purpose RAM	General Purpose RAM

Note 1: SFR file locations 10h - 17h are banked. The lower nibble of the BSR specifies the bank. All unbanked SFRs ignore the Bank Select Register (BSR) bits.

2: General Purpose Registers (GPR) locations 20h - FFh, 120h - 1FFh, 220h - 2FFh, and 320h - 3FFh are banked. The upper nibble of the BSR specifies this bank. All other GPRs ignore the Bank Select Register (BSR) bits.

3: RAM bank 3 is not implemented on the PIC17C752 and the PIC17C762. Reading any unimplemented register reads ‘0’s.

4: Bank 8 is only implemented on the PIC17C76X devices.

7.3 Stack Operation

PIC17C7XX devices have a 16 x 16-bit hardware stack (Figure 7-1). The stack is not part of either the program or data memory space, and the stack pointer is neither readable nor writable. The PC (Program Counter) is "PUSH'd" onto the stack when a CALL or LCALL instruction is executed, or an interrupt is acknowledged. The stack is "POP'd" in the event of a RETURN, RETLW, or a RETFIE instruction execution. PCLATH is not affected by a "PUSH" or a "POP" operation.

The stack operates as a circular buffer, with the stack pointer initialized to '0' after all RESETS. There is a stack available bit (STKAV) to allow software to ensure that the stack will not overflow. The STKAV bit is set after a device RESET. When the stack pointer equals Fh, STKAV is cleared. When the stack pointer rolls over from Fh to 0h, the STKAV bit will be held clear until a device RESET.

Note 1: There is not a status bit for stack underflow. The STKAV bit can be used to detect the underflow which results in the stack pointer being at the Top-of-Stack.

2: There are no instruction mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions, or the vectoring to an interrupt vector.

3: After a RESET, if a "POP" operation occurs before a "PUSH" operation, the STKAV bit will be cleared. This will appear as if the stack is full (underflow has occurred). If a "PUSH" operation occurs next (before another "POP"), the STKAV bit will be locked clear. Only a device RESET will cause this bit to set.

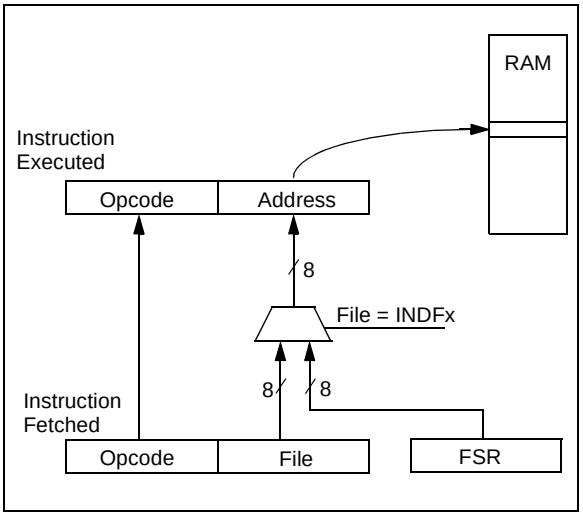
After the device is "PUSH'd" sixteen times (without a "POP"), the seventeenth push overwrites the value from the first push. The eighteenth push overwrites the second push (and so on).

7.4 Indirect Addressing

Indirect addressing is a mode of addressing data memory where the data memory address in the instruction is not fixed. That is, the register that is to be read or written can be modified by the program. This can be useful for data tables in the data memory. Figure 7-6 shows the operation of indirect addressing. This depicts the moving of the value to the data memory address specified by the value of the FSR register.

Example 7-1 shows the use of indirect addressing to clear RAM in a minimum number of instructions. A similar concept could be used to move a defined number of bytes (block) of data to the USART transmit register (TXREG). The starting address of the block of data to be transmitted could easily be modified by the program.

FIGURE 7-6: INDIRECT ADDRESSING



7.4.1 INDIRECT ADDRESSING REGISTERS

The PIC17C7XX has four registers for indirect addressing. These registers are:

- INDF0 and FSR0
- INDF1 and FSR1

Registers INDF0 and INDF1 are not physically implemented. Reading or writing to these registers activates indirect addressing, with the value in the corresponding FSR register being the address of the data. The FSR is an 8-bit register and allows addressing anywhere in the 256-byte data memory address range. For banked memory, the bank of memory accessed is specified by the value in the BSR.

If file INDF0 (or INDF1) itself is read indirectly via an FSR, all '0's are read (Zero bit is set). Similarly, if INDF0 (or INDF1) is written to indirectly, the operation will be equivalent to a NOP, and the status bits are not affected.

TABLE 10-17: PORTJ FUNCTIONS

Name	Bit	Buffer Type	Function
RJ0	bit0	ST	Input/output
RJ1	bit1	ST	Input/output
RJ2	bit2	ST	Input/output
RJ3	bit3	ST	Input/output
RJ4	bit4	ST	Input/output
RJ5	bit5	ST	Input/output
RJ6	bit6	ST	Input/output
RJ7	bit7	ST	Input/output

Legend: ST = Schmitt Trigger input

TABLE 10-18: REGISTERS/BITS ASSOCIATED WITH PORTJ

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on, POR, BOR	$\overline{\text{MCLR}}$, WDT
12h, Bank 8	DDRJ	Data Direction Register for PORTJ								1111 1111	1111 1111
13h, Bank 8	PORTJ	RJ7	RJ6	RJ5	RJ4	RJ3	RJ2	RJ1	RJ0	xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged

NOTES:

12.0 TIMER0

The Timer0 module consists of a 16-bit timer/counter, TMR0. The high byte is register TMR0H and the low byte is register TMR0L. A software programmable 8-bit prescaler makes Timer0 an effective 24-bit overflow timer. The clock source is software programmable as either the internal instruction clock, or an external clock on the RA1/T0CKI pin. The control bits for this module are in register T0STA (Figure 12-1).

REGISTER 12-1: T0STA REGISTER (ADDRESS: 05h, UNBANKED)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
INTEDG	T0SE	T0CS	T0PS3	T0PS2	T0PS1	T0PS0	—
bit 7							bit 0

bit 7 **INTEDG**: RA0/INT Pin Interrupt Edge Select bit
This bit selects the edge upon which the interrupt is detected.
1 = Rising edge of RA0/INT pin generates interrupt
0 = Falling edge of RA0/INT pin generates interrupt

bit 6 **T0SE**: Timer0 Clock Input Edge Select bit
This bit selects the edge upon which TMR0 will increment.

When T0CS = 0 (External Clock):
1 = Rising edge of RA1/T0CKI pin increments TMR0 and/or sets the T0CKIF bit
0 = Falling edge of RA1/T0CKI pin increments TMR0 and/or sets the T0CKIF bit

When T0CS = 1 (Internal Clock):
Don't care

bit 5 **T0CS**: Timer0 Clock Source Select bit
This bit selects the clock source for TMR0.
1 = Internal instruction clock cycle (T_{CY})
0 = External clock input on the T0CKI pin

bit 4-1 **T0PS3:T0PS0**: Timer0 Prescale Selection bits
These bits select the prescale value for TMR0.

T0PS3:T0PS0	Prescale Value
0000	1:1
0001	1:2
0010	1:4
0011	1:8
0100	1:16
0101	1:32
0110	1:64
0111	1:128
1xxx	1:256

bit 0 **Unimplemented**: Read as '0'

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR Reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

REGISTER 15-2: SSPCON1: SYNC SERIAL PORT CONTROL REGISTER1 (ADDRESS 11h, BANK 6)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	$\overline{\text{SSPM1}}$	$\overline{\text{SSPM0}}$
bit 7							bit 0

bit 7 **WCOL**: Write Collision Detect bit

Master mode:
1 = A write to the SSPBUF register was attempted while the I^2C conditions were not valid for a transmission to be started
0 = No collision

Slave mode:
1 = The SSPBUF register is written while it is still transmitting the previous word (must be cleared in software)
0 = No collision

bit 6 **SSPOV**: Receive Overflow Indicator bit

In SPI mode:
1 = A new byte is received while the SSPBUF register is still holding the previous data. In case of overflow, the data in SSPSR is lost. Overflow can only occur in Slave mode. In Slave mode, the user must read the SSPBUF, even if only transmitting data, to avoid setting overflow. In Master mode, the overflow bit is not set, since each new reception (and transmission) is initiated by writing to the SSPBUF register. (Must be cleared in software.)
0 = No overflow

In I^2C mode:
1 = A byte is received while the SSPBUF register is still holding the previous byte. SSPOV is a "don't care" in Transmit mode. (Must be cleared in software.)
0 = No overflow

bit 5 **SSPEN**: Synchronous Serial Port Enable bit
In both modes, when enabled, these pins must be properly configured as input or output.

In SPI mode:
1 = Enables serial port and configures SCK, SDO, SDI and $\overline{\text{SS}}$ as the source of the serial port pins
0 = Disables serial port and configures these pins as I/O port pins

In I^2C mode:
1 = Enables the serial port and configures the SDA and SCL pins as the source of the serial port pins
0 = Disables serial port and configures these pins as I/O port pins

Note: In SPI mode, these pins must be properly configured as input or output.

bit 4 **CKP**: Clock Polarity Select bit

In SPI mode:
1 = Idle state for clock is a high level
0 = Idle state for clock is a low level

In I^2C Slave mode:
SCK release control
1 = Enable clock
0 = Holds clock low (clock stretch). (Used to ensure data setup time.)

In I^2C Master mode:
Unused in this mode

bit 3-0 **SSPM3:SSPM0**: Synchronous Serial Port Mode Select bits
0000 = SPI Master mode, clock = FOSC/4
0001 = SPI Master mode, clock = FOSC/16
0010 = SPI Master mode, clock = FOSC/64
0011 = SPI Master mode, clock = TMR2 output/2
0100 = SPI Slave mode, clock = SCK pin, $\overline{\text{SS}}$ pin control enabled
0101 = SPI Slave mode, clock = SCK pin, $\overline{\text{SS}}$ pin control disabled, $\overline{\text{SS}}$ can be used as I/O pin
0110 = I^2C Slave mode, 7-bit address
0111 = I^2C Slave mode, 10-bit address
1000 = I^2C Master mode, clock = FOSC / (4 * (SSPADD+1))
1xx1 = Reserved
1x1x = Reserved

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR Reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

15.2.2 GENERAL CALL ADDRESS SUPPORT

The addressing procedure for the I^2C bus is such that the first byte after the START condition usually determines which device will be the slave addressed by the master. The exception is the general call address, which can address all devices. When this address is used, all devices should, in theory, respond with an acknowledge.

The general call address is one of eight addresses reserved for specific purposes by the I^2C protocol. It consists of all 0's with R/$\overline{W}$ = 0.

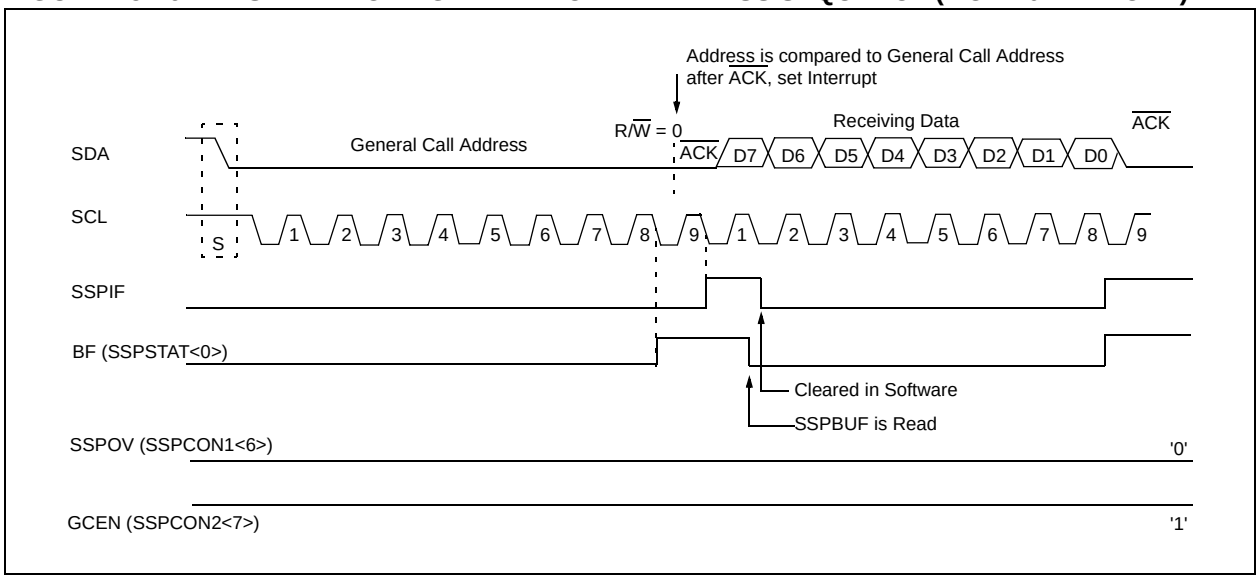
The general call address is recognized when the General Call Enable bit (GCEN) is enabled (SSPCON2<7> is set). Following a START bit detect, 8-bits are shifted into SSPSR and the address is compared against SSPADD and is also compared to the general call address, fixed in hardware.

If the general call address matches, the SSPSR is transferred to the SSPBUF, the BF flag is set (eighth bit) and on the falling edge of the ninth bit ($\overline{ACK}$ bit), the SSPIF flag is set.

When the interrupt is serviced, the source for the interrupt can be checked by reading the contents of the SSPBUF to determine if the address was device specific, or a general call address.

In 10-bit mode, the SSPADD is required to be updated for the second half of the address to match and the UA bit is set (SSPSTAT<1>). If the general call address is sampled when GCEN is set, while the slave is configured in 10-bit address mode, then the second half of the address is not necessary, the UA bit will not be set and the slave will begin receiving data after the acknowledge (Figure 15-16).

FIGURE 15-16: SLAVE MODE GENERAL CALL ADDRESS SEQUENCE (7 OR 10-BIT MODE)



15.2.6 MULTI-MASTER MODE

In Multi-Master mode, the interrupt generation on the detection of the START and STOP conditions allows the determination of when the bus is free. The STOP (P) and START (S) bits are cleared from a RESET, or when the MSSP module is disabled. Control of the I^2C bus may be taken when bit P (SSPSTAT<4>) is set, or the bus is idle, with both the S and P bits clear. When the bus is busy, enabling the SSP interrupt will generate the interrupt when the STOP condition occurs.

In Multi-Master operation, the SDA line must be monitored for arbitration, to see if the signal level is the expected output level. This check is performed in hardware, with the result placed in the BCLIF bit.

The states where arbitration can be lost are:

- Address Transfer
- Data Transfer
- A START Condition
- A Repeated Start Condition
- An Acknowledge Condition

15.2.7 I^2C MASTER MODE SUPPORT

Master mode is enabled by setting and clearing the appropriate SSPM bits in SSPCON1 and by setting the SSPEN bit. Once Master mode is enabled, the user has six options.

- Assert a START condition on SDA and SCL.
- Assert a Repeated Start condition on SDA and SCL.
- Write to the SSPBUF register initiating transmission of data/address.
- Generate a STOP condition on SDA and SCL.
- Configure the I^2C port to receive data.
- Generate an Acknowledge condition at the end of a received byte of data.

Note:	The MSSP Module, when configured in I^2C Master mode, does not allow queueing of events. For instance: The user is not allowed to initiate a START condition and immediately write the SSPBUF register to initiate transmission before the START condition is complete. In this case, the SSPBUF will not be written to and the WCOL bit will be set, indicating that a write to the SSPBUF did not occur.

15.2.7.1 I^2C Master Mode Operation

The master device generates all of the serial clock pulses and the START and STOP conditions. A transfer is ended with a STOP condition or with a Repeated Start condition. Since the Repeated Start condition is also the beginning of the next serial transfer, the I^2C bus will not be released.

In Master Transmitter mode, serial data is output through SDA, while SCL outputs the serial clock. The first byte transmitted contains the slave address of the receiving device (7 bits) and the Read/Write (R/$\overline{W}$) bit. In this case, the R/$\overline{W}$ bit will be logic '0'. Serial data is transmitted 8 bits at a time. After each byte is transmitted, an acknowledge bit is received. START and STOP conditions are output to indicate the beginning and the end of a serial transfer.

In Master Receive mode, the first byte transmitted contains the slave address of the transmitting device (7 bits) and the R/$\overline{W}$ bit. In this case, the R/$\overline{W}$ bit will be logic '1'. Thus, the first byte transmitted is a 7-bit slave address, followed by a '1' to indicate receive bit. Serial data is received via SDA, while SCL outputs the serial clock. Serial data is received 8 bits at a time. After each byte is received, an acknowledge bit is transmitted. START and STOP conditions indicate the beginning and end of transmission.

The baud rate generator used for SPI mode operation is now used to set the SCL clock frequency for either 100 kHz, 400 kHz, or 1 MHz I^2C operation. The baud rate generator reload value is contained in the lower 7 bits of the SSPADD register. The baud rate generator will automatically begin counting on a write to the SSPBUF. Once the given operation is complete (i.e., transmission of the last data bit is followed by ACK), the internal clock will automatically stop counting and the SCL pin will remain in its last state

17.4 Power-down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction. This clears the Watchdog Timer and postscaler (if enabled). The $\overline{PD}$ bit is cleared and the $\overline{TO}$ bit is set (in the CPUSTA register). In SLEEP mode, the oscillator driver is turned off. The I/O ports maintain their status (driving high,low, or hi-impedance input).

The $\overline{MCLR}/V_{PP}$ pin must be at a logic high level (V_{IHMC}). A WDT time-out RESET does not drive the $\overline{MCLR}/V_{PP}$ pin low.

17.4.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

- Power-on Reset
- Brown-out Reset
- External RESET input on $\overline{MCLR}/V_{PP}$ pin
- WDT Reset (if WDT was enabled)
- Interrupt from RA0/INT pin, RB port change, T0CKI interrupt, or some peripheral interrupts

The following peripheral interrupts can wake the device from SLEEP:

- Capture interrupts
- USART synchronous slave transmit interrupts
- USART synchronous slave receive interrupts
- A/D conversion complete
- SPI slave transmit/receive complete
- I^2C slave receive

Other peripherals cannot generate interrupts since during SLEEP, no on-chip Q clocks are present.

Any RESET event will cause a device RESET. Any interrupt event is considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits in the CPUSTA register can be used to determine the cause of a device RESET. The $\overline{PD}$ bit, which is set on power-up, is cleared when SLEEP is invoked. The $\overline{TO}$ bit is cleared if WDT time-out occurred (and caused a RESET).

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GLINTD bit. If the GLINTD bit is set (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GLINTD bit is clear (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt vector address. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

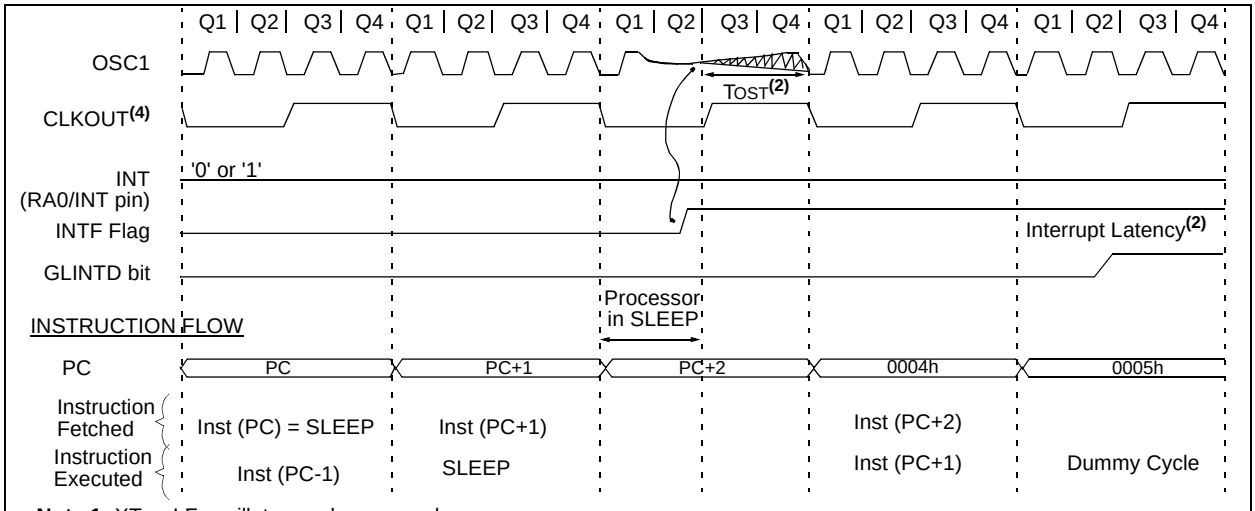
Note:	If the global interrupt is disabled (GLINTD is set), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bit set, the device will immediately wake-up from SLEEP. The $\overline{TO}$ bit is set and the $\overline{PD}$ bit is cleared.

The WDT is cleared when the device wakes from SLEEP, regardless of the source of wake-up.

17.4.1.1 Wake-up Delay

When the oscillator type is configured in XT or LF mode, the Oscillator Start-up Timer (OST) is activated on wake-up. The OST will keep the device in RESET for 1024TOSC. This needs to be taken into account when considering the interrupt response time when coming out of SLEEP.

FIGURE 17-2: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT or LF oscillator mode assumed.
2: TOST = 1024TOSC (drawing not to scale). This delay will not be there for RC osc mode.
3: When GLINTD = 0, processor jumps to interrupt routine after wake-up. If GLINTD = 1, execution will continue in line.
4: CLKOUT is not available in these osc modes, but shown here for timing reference.

INCF **Increment f**

Syntax: [*label*] INCF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (f) + 1 → (dest)

Status Affected: OV, C, DC, Z

Encoding:

0001	010d	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is 0, the result is placed in WREG. If 'd' is 1, the result is placed back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `INCF CNT, 1`

Before Instruction
CNT = 0xFF
Z = 0
C = ?

After Instruction
CNT = 0x00
Z = 1
C = 1

INCFSZ **Increment f, skip if 0**

Syntax: [*label*] INCFSZ f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (f) + 1 → (dest)
skip if result = 0

Status Affected: None

Encoding:

0001	111d	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is 0, the result is placed in WREG. If 'd' is 1, the result is placed back in register 'f'.
If the result is 0, the next instruction, which is already fetched is discarded and a NOP is executed instead, making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

Example:
```
HERE    INCFSZ  CNT, 1
NZERO   :
ZERO    :
```

Before Instruction
PC = Address (HERE)

After Instruction
CNT = CNT + 1
If CNT = 0;
PC = Address (ZERO)
If CNT ≠ 0;
PC = Address (NZERO)

MOVPF **Move p to f**

Syntax: [*label*] MOVPF p,f

Operands: $0 \le f \le 255$
$0 \le p \le 31$

Operation: (p) → (f)

Status Affected: Z

Encoding:

010p	pppp	ffff	ffff

Description: Move data from data memory location 'p' to data memory location 'f'. Location 'f' can be anywhere in the 256 byte data space (00h to FFh), while 'p' can be 00h to 1Fh.

Either 'p' or 'f' can be WREG (a useful, special situation).

MOVPF is particularly useful for transferring a peripheral register (e.g. the timer or an I/O port) to a data memory location. Both 'f' and 'p' can be indirectly addressed.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'p'	Process Data	Write register 'f'

Example:
```
MOVPF   REG1, REG2
```
Before Instruction
REG1 = 0x11
REG2 = 0x33

After Instruction
REG1 = 0x11
REG2 = 0x11

MOVWF **Move WREG to f**

Syntax: [*label*] MOVWF f

Operands: $0 \le f \le 255$

Operation: (WREG) → (f)

Status Affected: None

Encoding:

0000	0001	ffff	ffff

Description: Move data from WREG to register 'f'. Location 'f' can be anywhere in the 256 byte data space.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example:
```
MOVWF   REG
```
Before Instruction
WREG = 0x4F
REG = 0xFF

After Instruction
WREG = 0x4F
REG = 0x4F

SWAPF **Swap f**

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: f<3:0> → dest<7:4>;
f<7:4> → dest<3:0>

Status Affected: None

Encoding:

0001	110d	ffff	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in WREG. If 'd' is 1, the result is placed in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `SWAPF REG, 0`

Before Instruction
REG = 0x53

After Instruction
REG = 0x35

TABLRD **Table Read**

Syntax: [*label*] TABLRD t,i,f

Operands: $0 \le f \le 255$
$i \in [0,1]$
$t \in [0,1]$

Operation: If t = 1,
TBLATH → f;
If t = 0,
TBLATL → f;
Prog Mem (TBLPTR) → TBLAT;
If i = 1,
TBLPTR + 1 → TBLPTR
If i = 0,
TBLPTR is unchanged

Status Affected: None

Encoding:

1010	10ti	ffff	ffff

Description:
1. A byte of the table latch (TBLAT) is moved to register file 'f'.
   If t = 1: the high byte is moved;
   If t = 0: the low byte is moved.
2. Then, the contents of the program memory location pointed to by the 16-bit Table Pointer (TBLPTR) are loaded into the 16-bit Table Latch (TBLAT).
3. If i = 1: TBLPTR is incremented;
   If i = 0: TBLPTR is not incremented.

Words: 1

Cycles: 2 (3-cycle if f = PCL)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register TBLATH or TBLATL	Process Data	Write register 'f'
No operation	No operation (Table Pointer on Address bus)	No operation	No operation ($\overline{OE}$ goes low)

19.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - ICEPIC™ In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD for PIC16F87X
- Device Programmers
  - PRO MATE® II Universal Device Programmer
  - PICSTART® Plus Entry-Level Development Programmer
- Low Cost Demonstration Boards
  - PICDEM™ 1 Demonstration Board
  - PICDEM 2 Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 17 Demonstration Board
  - KEELOQ® Demonstration Board

19.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. The MPLAB IDE is a Windows®-based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor
- A project manager
- Customizable toolbar and key mapping
- A status bar
- On-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or ‘C’)
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file
  - machine code

The ability to use MPLAB IDE with multiple debugging tools allows users to easily switch from the cost-effective simulator to a full-featured emulator with minimal retraining.

19.2 MPASM Assembler

The MPASM assembler is a full-featured universal macro assembler for all PIC MCU’s.

The MPASM assembler has a command line interface and a Windows shell. It can be used as a stand-alone application on a Windows 3.x or greater system, or it can be used through MPLAB IDE. The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file that contains source lines and generated machine code, and a COD file for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects.
- User-defined macros to streamline assembly code.
- Conditional assembly for multi-purpose source files.
- Directives that allow complete control over the assembly process.

19.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI ‘C’ compilers for Microchip’s PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

FIGURE 20-15: SPI SLAVE MODE TIMING (CKE = 0)

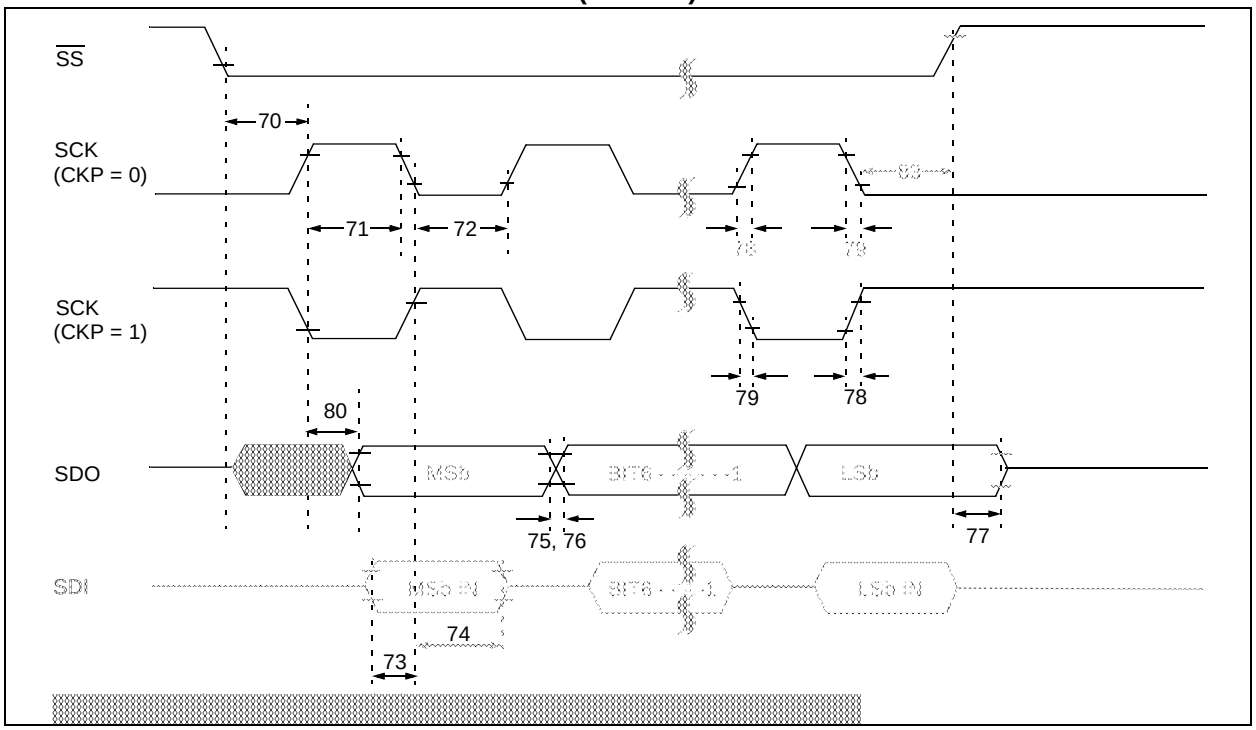


TABLE 20-10: SPI MODE REQUIREMENTS (SLAVE MODE TIMING, CKE = 0)

Param. No.	Symbol	Characteristic		Min	Typ†	Max	Units	Conditions
70	TssL2scH, TssL2scL	$\overline{SS}$↓ to SCK↓ or SCK↑ input		Tcy	—	—	ns	
71	TscH	SCK input high time (Slave mode)	Continuous	1.25TCY + 30	—	—	ns	
71A			Single Byte	40	—	—	ns	**(Note 1)**
72	TscL	SCK input low time (Slave mode)	Continuous	1.25TCY + 30	—	—	ns	
72A			Single Byte	40	—	—	ns	**(Note 1)**
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
73A	TB2B	Last clock edge of Byte1 to the 1st clock edge of Byte2		1.5TCY + 40	—	—	ns	**(Note 1)**
74	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
75	TdoR	SDO data output rise time		—	10	25	ns	
76	TdoF	SDO data output fall time		—	10	25	ns	
77	TssH2doZ	$\overline{SS}$↑ to SDO output hi-impedance		10	—	50	ns	
78	TscR	SCK output rise time (Master mode)		—	10	25	ns	
79	TscF	SCK output fall time (Master mode)		—	10	25	ns	
80	TscH2doV, TscL2doV	SDO data output valid after SCK edge		—	—	50	ns	
83	TscH2ssH, TscL2ssH	$\overline{SS}$ ↑ after SCK edge		1.5TCY + 40	—	—	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

Note 1: Specification 73A is only required if specifications 71A and 72A are used.

Param No.	Sym	Characteristic		Min	Max	Units	Conditions
110	Tbuf	Bus free time	100 kHz mode	4.7	—	ms	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	ms	
			1 MHz mode(1)	0.5	—	ms	
D102	Cb	Bus capacitive loading		—	400	pF	

Note 1: Maximum pin capacitance = 10 pF for all I^2C pins.

2: A fast mode (400 KHz) I^2C bus device can be used in a standard mode I^2C bus system, but the parameter # 107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line. Parameter #102 + #107 = 1000 + 250 = 1250 ns (for 100 kHz mode) before the SCL line is released.

3: C_b is specified to be from 10-400pF. The minimum specifications are characterized with C_b=10pF. The rise time spec (t_r) is characterized with R_p=R_p min. The minimum fall time specification (t_f) is characterized with C_b=10pF,and R_p=R_p max. These are only valid for fast mode operation (V_{DD}=4.5-5.5V) and where the SPM bit (SSPSTAT<7>) =1.)

4: Max specifications for these parameters are valid for falling edge only. Specs are characterized with R_p=R_p min and C_b=400pF for standard mode, 200pF for fast mode, and 10pF for 1MHz mode.

FIGURE 20-19: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

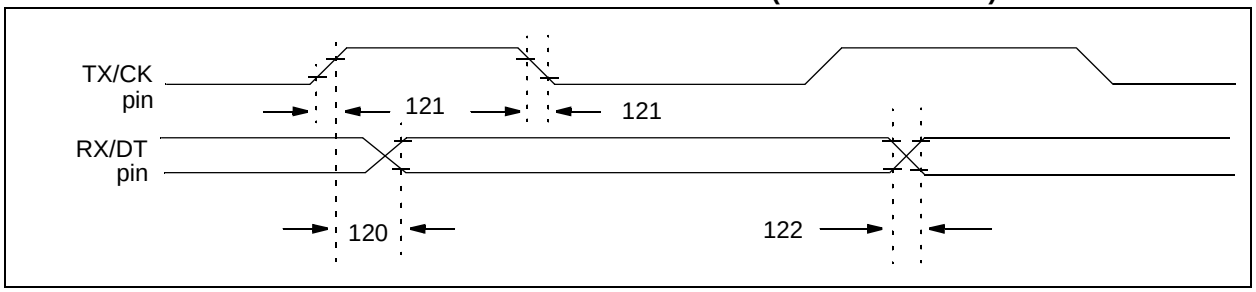


TABLE 20-14: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

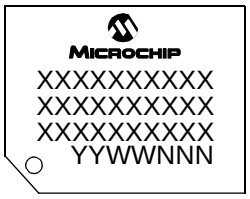
Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	PIC17**C**XXX	—	—	50	ns	
			PIC17**LC**XXX	—	—	75	ns	
121	TckRF	Clock out rise time and fall time (Master mode)	PIC17**C**XXX	—	—	25	ns	
			PIC17**LC**XXX	—	—	40	ns	
122	TdtRF	Data out rise time and fall time	PIC17**C**XXX	—	—	25	ns	
			PIC17**LC**XXX	—	—	40	ns	

† Data in “Typ” column is at 5V, 25°C unless otherwise stated.

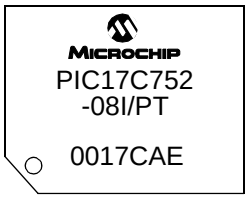
22.0 PACKAGING INFORMATION

22.1 Package Marking Information

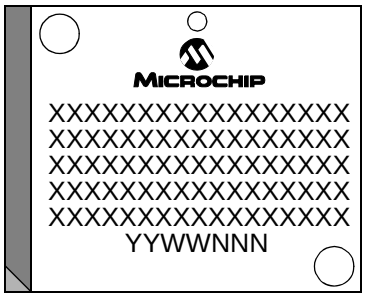
64-Lead TQFP



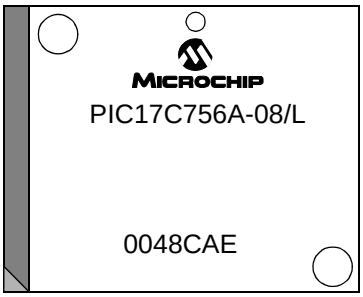
Example



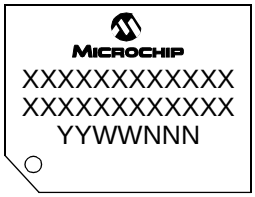
68-Lead PLCC



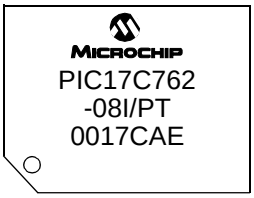
Example



80-Lead TQFP



Example

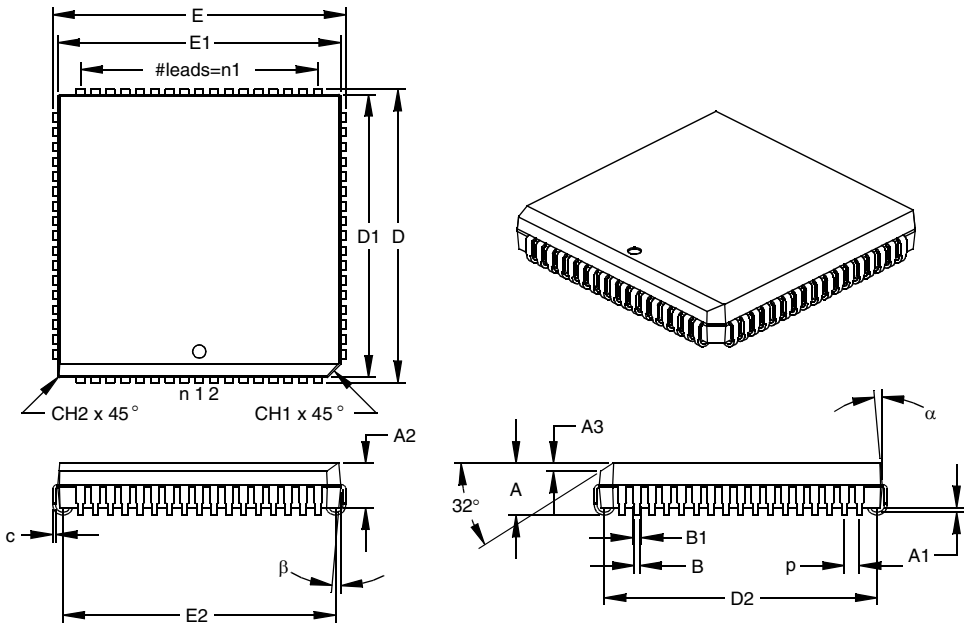


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

68-Lead Plastic Leaded Chip Carrier (L) – Square (PLCC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

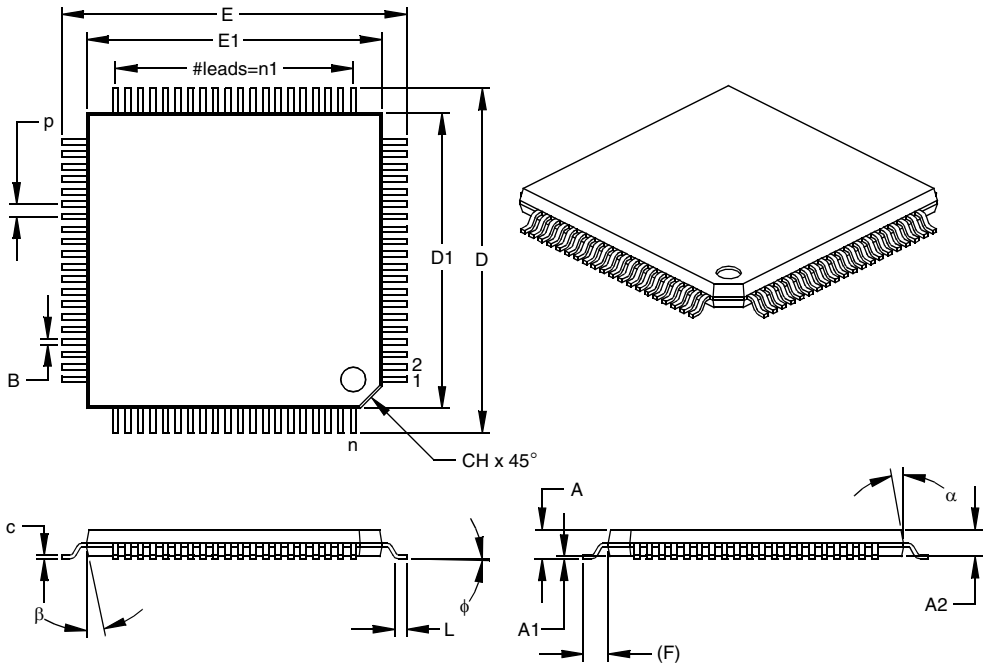


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		68			68	
Pitch	p		.050			1.27	
Pins per Side	n1		17			17	
Overall Height	A	.165	.173	.180	4.19	4.39	4.57
Molded Package Thickness	A2	.145	.153	.160	3.68	3.87	4.06
Standoff §	A1	.020	.028	.035	0.51	0.71	0.89
Side 1 Chamfer Height	A3	.024	.029	.034	0.61	0.74	0.86
Corner Chamfer 1	CH1	.040	.045	.050	1.02	1.14	1.27
Corner Chamfer (others)	CH2	.000	.005	.010	0.00	0.13	0.25
Overall Width	E	.985	.990	.995	25.02	25.15	25.27
Overall Length	D	.985	.990	.995	25.02	25.15	25.27
Molded Package Width	E1	.950	.954	.958	24.13	24.23	24.33
Molded Package Length	D1	.950	.954	.958	24.13	24.23	24.33
Footprint Width	E2	.890	.920	.930	22.61	23.37	23.62
Footprint Length	D2	.890	.920	.930	22.61	23.37	23.62
Lead Thickness	c	.008	.011	.013	0.20	0.27	0.33
Upper Lead Width	B1	.026	.029	.032	0.66	0.74	0.81
Lower Lead Width	B	.013	.020	.021	0.33	0.51	0.53
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-047
Drawing No. C04-049

80-Lead Plastic Thin Quad Flatpack (PT) 12x12x1 mm Body, 1.0/0.10 mm Lead Form (TQFP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		80			80	
Pitch	p		.020			0.50	
Pins per Side	n1		20			20	
Overall Height	A	.039	.043	.047	1.00	1.10	1.20
Molded Package Thickness	A2	.037	.039	.041	0.95	1.00	1.05
Standoff §	A1	.002	.004	.006	0.05	0.10	0.15
Foot Length	L	.018	.024	.030	0.45	0.60	0.75
Footprint (Reference)	(F)		.039			1.00	
Foot Angle	ϕ	0	3.5	7	0	3.5	7
Overall Width	E	.541	.551	.561	13.75	14.00	14.25
Overall Length	D	.541	.551	.561	13.75	14.00	14.25
Molded Package Width	E1	.463	.472	.482	11.75	12.00	12.25
Molded Package Length	D1	.463	.472	.482	11.75	12.00	12.25
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.007	.009	.011	0.17	0.22	0.27
Pin 1 Corner Chamfer	CH	.025	.035	.045	0.64	0.89	1.14
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-026
Drawing No. C04-092